

Statement of Volatility – Dell EMC PowerEdge R540

Dell EMC PowerEdge R540 contains both volatile and non-volatile (NV) components. Volatile components lose their data immediately upon removal of power from the component. Non-volatile components continue to retain their data even after the power has been removed from the component. Components chosen as user-definable configuration options (those not soldered to the motherboard) are not included in the Statement of Volatility. Configuration option information (pertinent to options such as microprocessors, remote access controllers, and storage controllers) is available by component separately. The following NV components are present in the PowerEdge R540 server.

Item	Non-Volatile or Volatile	Quantity	Reference Designator	Size
Planer				
PCH Internal CMOS RAM	Non-Volatile	1	U_PCH1	256 Bytes
BIOS SPI Flash	Non-Volatile	1	U_PRIM_SPI_BIOS	32 MB
BIOS Recovery SPI Flash	Non-Volatile	1	U_RECROM	16 MB
iDRAC SPI Flash	Non-Volatile	1	U_UBOOT	4 MB
BMC EMMC	Non-Volatile	1	U_EMMC1	8 GB
System CPLD RAM	Volatile	1	U_CPLD1	16 KB
System Memory	Volatile	Up to 10 for CPU1	CPU1: A1~A10,	Up to 32GB per DIMM (RDIMM)
		Up to 6 for CPU2	CPU2: B1~B6	Up to 64GB per DIMM (LRDIMM)
Internal USB Key	Non-Volatile	1	J_USB3_INT	Varies (not factory installed)
Trusted Platform Module (TPM, TPM 2.0 only)	Non-Volatile	1	J_TPM_MODULE	128 Bytes
CPU Vcore and VSA Regulators	Non-Volatile	1 for CPU1, 1 for CPU2	PAAU1 PBAU1	16KB
Memory VDDQ Regulators	Non-Volatile	2 for CPU1, 2 for CPU2	PAEU2, PAFU2 PBEU2, PBFU2	16KB
LOM NVRAM	Non-Volatile	1	U_LOM1_ROM	1 MB
Power Supplies				
Microcontroller	Non-Volatile	Up to 2	Microchip	Up to 64KB

Item	Non-Volatile or Volatile	Quantity	Reference Designator	Size
2U 2x3.5" Rear Backplane				
SEP internal flash	Non-Volatile	1	U_SEP	Flash:64KB EEPROM:2KB
2U 8x3.5" Backplane				
SEP internal flash	Non-Volatile	1	U_SEP	Flash:64KB EEPROM:2KB
2U 12x3.5" EXP/Back	plane			
NVSRAM memory	Non-Volatile	1	U_NVSRAM	MRAM: 1 Mb
Flash memory	Non-Volatile	1	U_FLASH	Flash: 128 Mb
Expander FRU image	Non-Volatile	1	U_EXP_EEPROM	512 Bytes
BP FRU image	Non-Volatile	1	U_BP_EEPROM	256 Bytes
H740, H740P, H840 PE	RC			
NVSRAM memory	Non-Volatile	1	U1087	128KB
FRU	Non-Volatile	1	U1019	256B
SPD	Non-Volatile	1	U22	256B
Flash	Non-Volatile	1	U1086	16MB
Backup Flash	Non-Volatile	1	U1100	8GB
SDRAM	Volatile	9	U1077-U1085	8GB
H330 PERC				
NVSRAM memory	Non-Volatile	1	U1033	128KB
FRU	Non-Volatile	1	U1019	256B
1-Wire EEPROM	Non-Volatile	1	U1004	128B
SBR	Non-Volatile	1	U1020	8KB
Flash	Non-Volatile	1	U3	16MB
HBA 330 PERC				
NVSRAM memory	Non-Volatile	1	U1033	128KB
FRU	Non-Volatile	1	U1019	256B
Serial Boot ROM	Non-Volatile	1	U1020	8KB
Flash	Non-Volatile	1	U3	16MB
Left (Quick Sync 2.0 module) Ear				

Item	Non-Volatile or Volatile	Quantity	Reference Designator	Size
MCU	Non-Volatile	1	USAM7	32Mb
Left (status) Ear				
MCU	Non-Volatile	1	U_TINY	8KB
Right Ear				
SPI Flash	Non-Volatile	1	U2	32Mb
ТРМ				
Trusted Platform Module (TPM, TPM 2.0 only)	Non-Volatile	1	U_TPM	128 Bytes
IDSDM - vFlash				
vFlash (uSD)	Non-Volatile	1	J3	16GB
iDSDM (uSD1, uSD2)	Non-Volatile	2	J1, J2	16GB, 32GB, 64GB
SPI Flash	Non-Volatile	1	U2	1MB
BOSS				
SPI Flash	Non-Volatile	1	U17	1024KB
TFRU	Non-Volatile	1	U7	64KB
LCD Bezel				
Microcontroller	Non-Volatile	1	IC1	256KB

Item	Type (e.g. Flash PROM, EEPROM)	Can user programs or operating system write data to it during normal operation?	Purpose? (e.g. boot code)
Planer			
PCH Internal CMOS RAM	Battery-backed CMOS RAM	No	Real-time clock and BIOS configuration settings
BIOS SPI Flash	SPI Flash	Yes	Boot code, system configuration information, UEFI environment, Flash Disceptor, ME
BIOS Recovery SPI Flash	SPI Flash	No	16MB Recovery SPI ROM exits as an aid to reprogram the primary ROM
iDRAC SPI Flash	SPI Flash	No	iDRAC Uboot (bootloader), server managent persistent store (i.e. IDRAC MAC Address, iDRAC boot variables), lifecycle log cache, virtual planar FRU and EPPID, rac log, System Event Log,
BMC EMMC	eMMC NAND Flash	No	Operational iDRAC FW, Lifecycle Controller (LC) USC partition, LC service diags, LC OS drivers, USC firmware
Memory VDDQ, CPU Vcore and VSA Regulators	OTP(one time programmable)	No	Operational parameters
System CPLD RAM	RAM	No	Not utilized
System Memory	RAM	Yes	System OS RAM
Internal USB Key	Flash	Yes	General purpose USB key drive
Trusted Platform Module (TPM, TPM 2.0 only)	EEPROM	Yes	Storage of encryption keys
Power Supplies			
Microcontroller	Flash PROM and EEPROM	Yes	Report PSU information and control firmware
2U 2x3.5" Rear Backplane			
SEP internal flash	Flash	No	FW configuration data

ltem	Type (e.g. Flash PROM, EEPROM)	Can user programs or operating system write data to it during normal operation?	Purpose? (e.g. boot code)
SEP internal EEPROM	EEPROM	No	FRU
2U 8x3.5" Backplane			
SEP internal flash	Flash	No	FW configuration data
SEP internal EEPROM	EEPROM	No	FRU
2U 12x3.5" EXP/Backplan	e		
NVSRAM memory	MRAM	No	Configuration data
Flash memory	Flash	No	Card firmware
Expander FRU image	EEPROM	No	FRU
BP FRU image	EEPROM	No	FRU
H740, H740P, H840 PERC			
NVSRAM memory	NVSRAM	No	Configuration data
FRU	FRU	No	Card manufacturing information
SPD	SPD	No	Memory configuration data
Flash	Flash	No	Card firmware
Backup Flash	Backup Flash	No	Holds cache data during power loss
SDRAM	SDRAM	No	Cache for HDD I/O
H330 PERC			
NVSRAM memory	NVSRAM	No	Configuration data
FRU	FRU	No	Card manufacturing information
1-Wire EEPROM	1-Wire EEPROM	No	Holds default controller properties/settings
SBR	SBR	No	Boot loader
Flash	Flash	No	Card firmware
HBA 330 PERC			

Item	Type (e.g. Flash PROM, EEPROM)	Can user programs or operating system write data to it during normal operation?	Purpose? (e.g. boot code)
NVSRAM memory	NVSRAM	No	Configuration data
FRU	FRU	No	Card manufacturing information
Serial Boot ROM	Serial Boot ROM	No	Boot loader
Flash	Flash	No	Card firmware
Left (Quick Sync 2.0 modul	e) Ear		
MCU	embedded Flash	No	Card firmware
Left (status) Ear			
MCU	embedded Flash	No	Card firmware
Right Ear			
SPI Flash	SPI Flash	No	For field maintenance. Have License, Service Tag and system information.
TPM			
Trusted Platform Module (TPM, TPM 2.0 only)	EEPROM	Yes	Storage of encryption keys
IDSDM - vFlash			
vFlash (uSD)	NAND flash	Yes	Populate out-of-band or optionally connect to the host as mass storage and boot mechanism
iDSDM (uSD1, uSD2)	NAND flash	Yes	Provides mass storage
SPI Flash	SPI Flash	It is only indirectly connected to iDRAC. iDRAC can read any address in the SPI flash, but may only write the primary firmware storage area as a part of a firmware update procedure.	Boot firmware storage, configuration and state data for IDSDM.
BOSS			

Item	Type (e.g. Flash PROM, EEPROM)	Can user programs or operating system write data to it during normal operation?	Purpose? (e.g. boot code)
SPI Flash	FLASH EEPROM	No	Boot code, FW
TFRU	FLASH EEPROM	Yes	Thermal monitoring
LCD Bezel			
Microcontroller	Internal Flash	No	Boot loader and s/w implementation of LCD command set

Item	How is data input to this	How is this memory write	How is the memory
recin	memory?	protected?	cleared?
Planer	, , .	, r	
PCH Internal CMOS RAM	BIOS	N/A – BIOS only control	1) Set NVRAM_CLR jumper to clear BIOS configuration settings at boot and reboot system. 2) Power off the system, remove coin cell battery for 30 seconds, replace battery and then power back on. 3) Restore default configuration in F2 system setup menu.
BIOS SPI Flash	SPI interface via iDRAC	Software write protected	Not possible with any utilities or applications and system is not functional if corrupted or removed.
BIOS Recovery SPI Flash	SPI interface via PCH	Software write protected	Not possible with any utilities or applications and the system is not functional if BIOS SPI is corrupted or removed.
iDRAC SPI Flash	SPI interface via iDRAC	Embedded iDRAC subsystem firmware actively controls sub area based write protection as needed.	The user cannot clear memory completely. However, user data, lifecycle log and archive, SEL, and fw image repository can be cleared using Delete Configuration and Retire System, which can be accessed through the Lifecycle Controller interface.
BMC EMMC	NAND Flash interface via iDRAC	Embedded FW write protected	The user cannot clear memory completely. However, user data, lifecycle log and archive, SEL, and fw image repository can be cleared using Delete Configuration and Retire System, which can be accessed through the Lifecycle Controller interface.
Memory VDDQ, CPU Vcore and VSA Regulators	Once values are loaded into register space a cmd writes to nvm.	There are passwords for different sections of the register space	The user cannot clear memory.
System CPLD RAM	Not utilized	Not accessible	Not accessible
System Memory	System OS	OS Control	Reboot or power down

Item	How is data input to this memory?	How is this memory write protected?	How is the memory cleared?
			system
Internal USB Key	USB interface via PCH. Accessed via system OS	No write protect	Can be cleared in the system OS
Trusted Platform Module (TPM, TPM 2.0 only)	Using TPM Enabled operating systems	SW write protected	F2 Setup option
Power Supplies			
Microcontroller	The data is flash via Dell Update Package(DUP)	Using signature and manufacture key to protect memory write	Before firmware update, the memory will be clear.
2U 2x3.5" Rear Backplane			
SEP internal flash	Pre-programmed before assembly	Not WP	The user cannot clear memory.
SEP internal EEPROM	Programmed at ICT during production.	Not WP	The user cannot clear memory.
2U 8x3.5" Backplane			
SEP internal flash	Pre-programmed before assembly	Not WP	The user cannot clear memory.
SEP internal EEPROM	Programmed at ICT during production.	Not WP	The user cannot clear memory.
2U 12x3.5" EXP/Backplane			
NVSRAM memory	ROC writes configuration data to NVSRAM	Not WP. Not visible to Host Processor	Cannot be cleared with existing tools available to the customer
Flash memory	Pre-programmed before assembly. Can be updated using Dell/LSI tools	Not WP. Not visible to Host Processor	Cannot be cleared with existing tools available to the customer
Expander FRU image	Programmed at ICT during production.	Not WP	The user cannot clear memory.
BP FRU image	Programmed at ICT during production.	Not WP	The user cannot clear memory.
H740, H740P, H840 PERC			
NVSRAM memory	ROC writes configuration data to NVSRAM	Not WP. Not visible to Host Processor	User cannot clear the memory.
FRU	Programmed at ICT during production.	Not WP	User cannot clear the memory.
SPD	Pre-programmed before assembly	Not WP. Not visible to Host Processor	User cannot clear the memory.
Flash	Pre-programmed before assembly. Can be updated using Dell/LSI tools	Not WP. Not visible to Host Processor	User cannot clear the memory.
Backup Flash	FPGA backs up DDR data	Not WP. Not visible to	Flash can be cleared by

Item	How is data input to this	How is this memory write	How is the memory
	memory?	protected?	cleared?
	to this device in case of a	Host Processor	powering up the card and
	power failure		allowing the controller to
			flush the contents to VDs.
			If the VDs are no longer
			available, cache can be
			cleared by going into
			controller BIOS and
			selecting Discard
			Preserved Cache.
SDRAM	ROC writes to this	Not WP. Not visible to	Cache can be cleared by
	memory - using it as cache	Host Processor	powering off the card
Hogo DEDO	for data IO to HDDs		
H330 PERC			
NVSRAM memory	ROC writes configuration	Not WP. Not visible to	Cannot be cleared with
	data to NVSRAM	Host Processor	existing tools available to
			the customer
FRU	Programmed at ICT during	Not WP	Cannot be cleared with
	production.		existing tools available to
			the customer
1-Wire EEPROM	ROC writes data to this	Not WP. Not visible to	Cannot be cleared with
	memory	Host Processor	existing tools available to
			the customer
SBR	Pre-programmed before	Not WP. Not visible to	Cannot be cleared with
	assembly	Host Processor	existing tools available to
			the customer
Flash	Pre-programmed before	Not WP. Not visible to	Cannot be cleared with
	assembly. Can be updated	Host Processor	existing tools available to
	using Dell/LSI tools		the customer
HBA 330 PERC			
NVSRAM memory	ROC writes configuration	No write protect. Not	The user cannot clear
	data to NVSRAM	visible to Host Processor	memory.
FRU	Programmed at ICT during	No write protect	The user cannot clear
	production		memory.
Serial Boot ROM	Pre-programmed before	No write protect. Not	The user cannot clear
	assembly	visible to Host Processor	memory.
Flash	Pre-programmed before	No write protect. Not	The user cannot clear
	assembly. Can be updated	visible to Host Processor	memory.
	using Dell/LSI tools		,
Left (Quick Sync 2.0 module)	Ear		
MCU	Pre-programmed before	N/A	The user cannot clear
	assembly	,···	memory.
Left (status) Ear	<u>'</u>		<u>'</u>
MCU	Pre-programmed before	N/A	The user cannot clear
	assembly	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	memory.
Right Ear			, memory.
SPI Flash	CDI interfere via IDDAC	Hordwore stransis =	The user commet stars
	SPI interface via iDRAC	Hardware strapping	The user cannot clear
			memory.
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Item	How is data input to this memory?	How is this memory write protected?	How is the memory cleared?
TPM	, memory.	protecteur.	Cicurcur
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Trusted Platform Module (TPM, TPM 2.0 only)	Using TPM Enabled operating systems	SW write protected	F2 Setup option
IDSDM - vFlash			
vFlash (uSD)	Hear oan provide data to	No write protect	1. The card may be
	User can provide data to iDRAC (entirely in the iDRAC domain) to be pushed into vFlash	No write protect	1. The card may be physically removed and destroyed or cleared via standard means on a separate computer. Or 2. The user has access to the card in the host domain and may clear it manually.
iDSDM (uSD1, uSD2)	Device resides in host domain; they are exposed to the user via an internally connected, non- removable USB mass storage device	Physical write protect switch on ACE card	(1) card may be physically removed and destroyed or cleared via standard means on a separate computer OR (2)User has access to the card in the host domain and may clear it manually
SPI Flash	User can initiate a firmware update of the IDSDM device.	There is no mechanism provided to iDRAC to write any SPI NOR area outside of the primary IDSDM firmware region.	iDRAC may issue a clear command to erase all contents of the SPI NOR, but doing this will leave the IDSDM non-functional.
BOSS			
SPI Flash	By programming the image via firmware update process	N/A	Use Flash tool, type "go.nsh w y"
TFRU	During Manufacturing, by programming the image via firmware update process. During runtime, by I2C Proprietary Command Protocol	N/A	By writing to Flash
LCD Bezel			
Microcontroller	Updated as part of secure iDRAC software update. Configuration parameters can change only as part of iDRAC update	Writes are only allowed as part of secure iDRAC update	not user clearable.



NOTE: For any information that you may need, direct your questions to your Dell Marketing contact.

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